

| L Number | Hits | Search Text | DB | Time stamp |
|----------|-------|--|-------|------------------|
| 1 | 10831 | (encapsulant or (encapsulating adj material)) | USPAT | 2002/09/24 16:16 |
| 2 | 440 | ((encapsulant or (encapsulating adj material))) and (thermoset\$4 adj resin) | USPAT | 2002/09/24 16:17 |
| 3 | 275 | ((((encapsulant or (encapsulating adj material))) and (thermoset\$4 adj resin)) and (bisphenol or phenol\$3 or novola\$2)) | USPAT | 2002/09/24 16:34 |
| 4 | 161 | (((((encapsulant or (encapsulating adj material))) and (thermoset\$4 adj resin)) and (bisphenol or phenol\$3 or novola\$2)) and (IC or semiconductor or chip)) | USPAT | 2002/09/24 16:18 |
| 5 | 33 | (((((encapsulant or (encapsulating adj material))) and (thermoset\$4 adj resin)) and (bisphenol or phenol\$3 or novola\$2)) and (IC or semiconductor or chip)) and (dielectric adj constant) | USPAT | 2002/09/24 16:19 |
| 6 | 102 | (((((encapsulant or (encapsulating adj material))) and (thermoset\$4 adj resin)) and (bisphenol or phenol\$3 or novola\$2)) and (IC or semiconductor or chip)) and (colorant or pigment or (carbon adj black)) | USPAT | 2002/09/24 16:19 |
| 7 | 24 | ((((((encapsulant or (encapsulating adj material))) and (thermoset\$4 adj resin)) and (bisphenol or phenol\$3 or novola\$2)) and (IC or semiconductor or chip)) and (colorant or pigment or (carbon adj black))) and (dielectric adj constant) | USPAT | 2002/09/24 16:20 |
| 8 | 213 | ((encapsulant or (encapsulating adj material))) and (thermoset\$4 adj resin)) and ((bisphenol or phenol\$3 or novola\$2) and (epoxy adj resin)) | USPAT | 2002/09/24 16:34 |
| 10 | 3 | (((((encapsulant or (encapsulating adj material))) and (thermoset\$4 adj resin)) and ((bisphenol or phenol\$3 or novola\$2) and (epoxy adj resin))) and (cavity or opening)) and (embed\$4 near (IC or component or semiconductor or chip or die)) | USPAT | 2002/09/24 16:39 |
| 12 | 2 | ((((((encapsulant or (encapsulating adj material))) and (thermoset\$4 adj resin)) and ((bisphenol or phenol\$3 or novola\$2) and (epoxy adj resin))) and (cavity or opening)) and (embed\$4 near (IC or component or semiconductor or chip or die))) and (dye or (carbon adj black) or pigment or colorant)) and (dielectric adj constant) | USPAT | 2002/09/24 16:40 |
| 11 | 3 | ((((((encapsulant or (encapsulating adj material))) and (thermoset\$4 adj resin)) and ((bisphenol or phenol\$3 or novola\$2) and (epoxy adj resin))) and (cavity or opening)) and (embed\$4 near (IC or component or semiconductor or chip or die))) and (dye or (carbon adj black) or pigment or colorant) | USPAT | 2002/09/24 16:47 |
| 9 | 73 | (((((encapsulant or (encapsulating adj material))) and (thermoset\$4 adj resin)) and ((bisphenol or phenol\$3 or novola\$2) and (epoxy adj resin))) and (cavity or opening)) | USPAT | 2002/09/24 16:47 |
| 13 | 166 | (((((encapsulant or (encapsulating adj material))) and (thermoset\$4 adj resin)) and (bisphenol or phenol\$3 or novola\$2)) and (dye or (carbon adj black) or pigment or colorant)) | USPAT | 2002/09/24 16:47 |

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|----|----|---|-------|---------------------|
| 14 | 34 | (((encapsulant or (encapsulating adj material))) and (thermoset\$4 adj resin)) and (bisphenol or phenol\$3 or novola\$2)) and (dye or (carbon adj black) or pigment or colorant)) and (dielectric adj constant) | USPAT | 2002/09/24 16:48 |
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